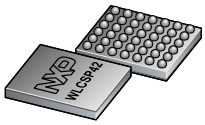

SOT1459-7

WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 2.86 mm x 2.46 mm x 0.525 mm body (backside coating included)

25 May 2020 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP42
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	13-05-2020
Manufacturer package code	98ASA01565D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.83	2.86	2.89	mm
package width	2.43	2.46	2.49	mm
package height	-	0.525	0.565	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	42	-	

WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 2.86 mm x 2.46 mm x 0.525 mm body (backside coating included)

2 Package outline

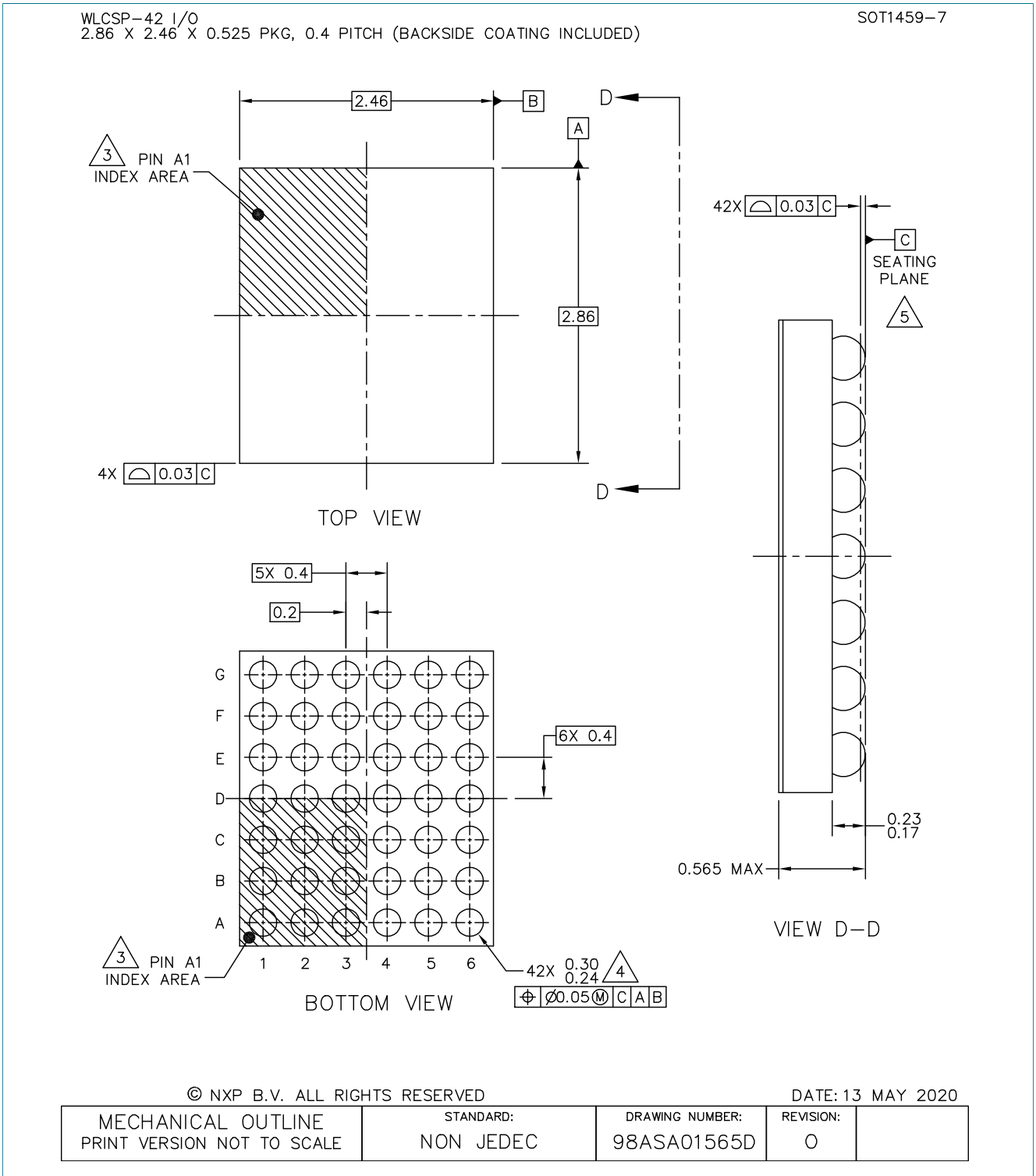

Figure 1. Package outline WLCSP42 (SOT1459-7)

3 Soldering

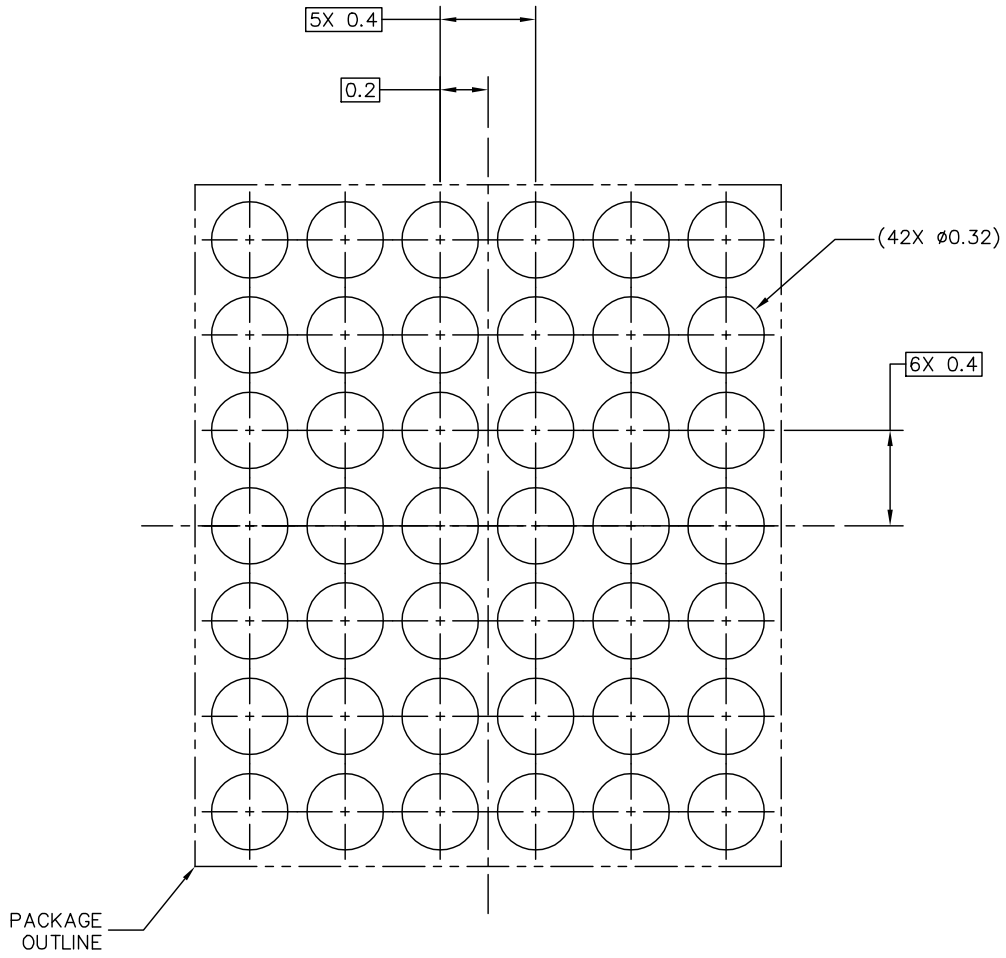

Figure 2. Reflow soldering footprint part1 for WLCSP42 (SOT1459-7)

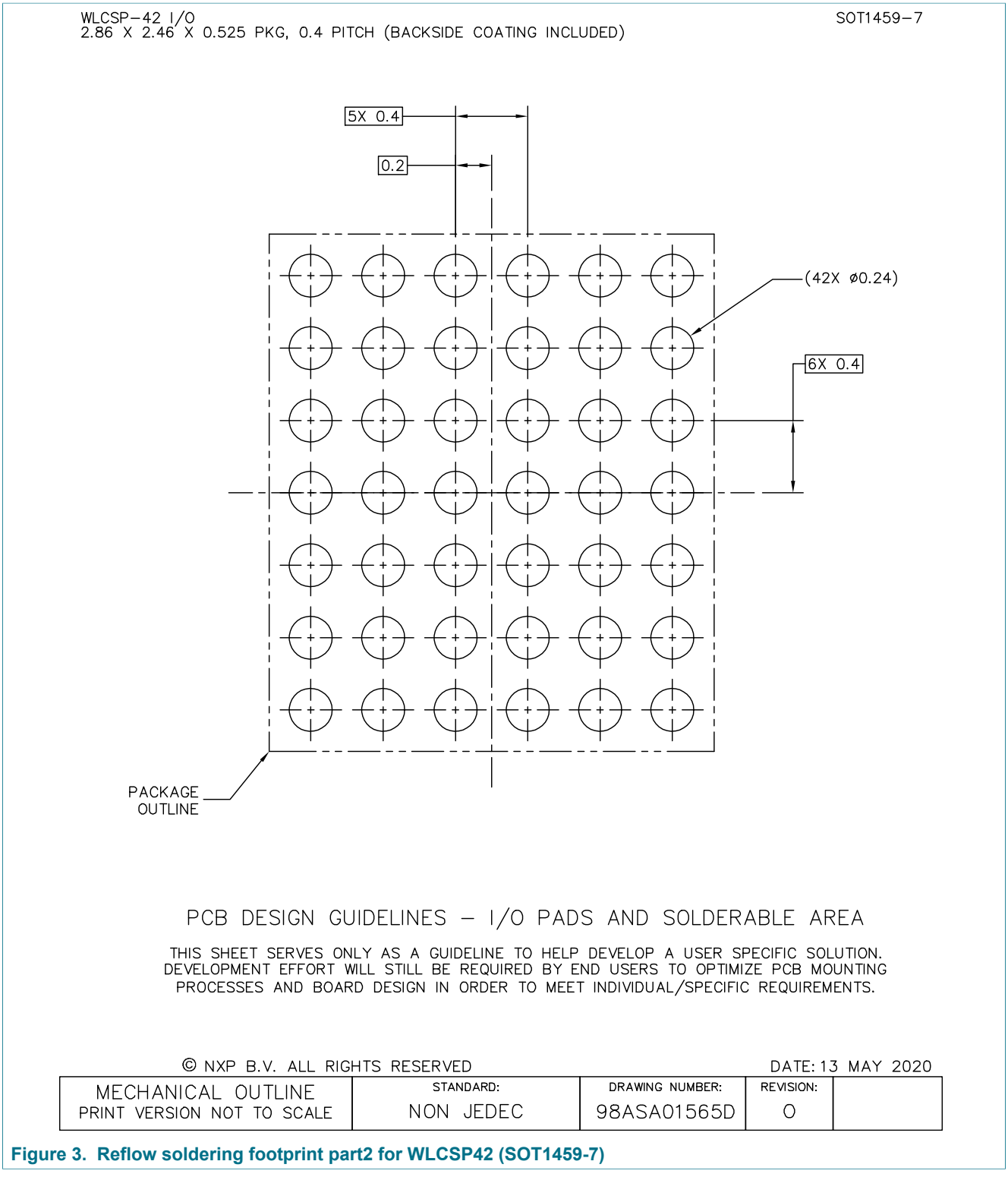

Figure 3. Reflow soldering footprint part2 for WLCSP42 (SOT1459-7)

WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 2.86 mm x 2.46 mm x 0.525 mm body (backside coating included)

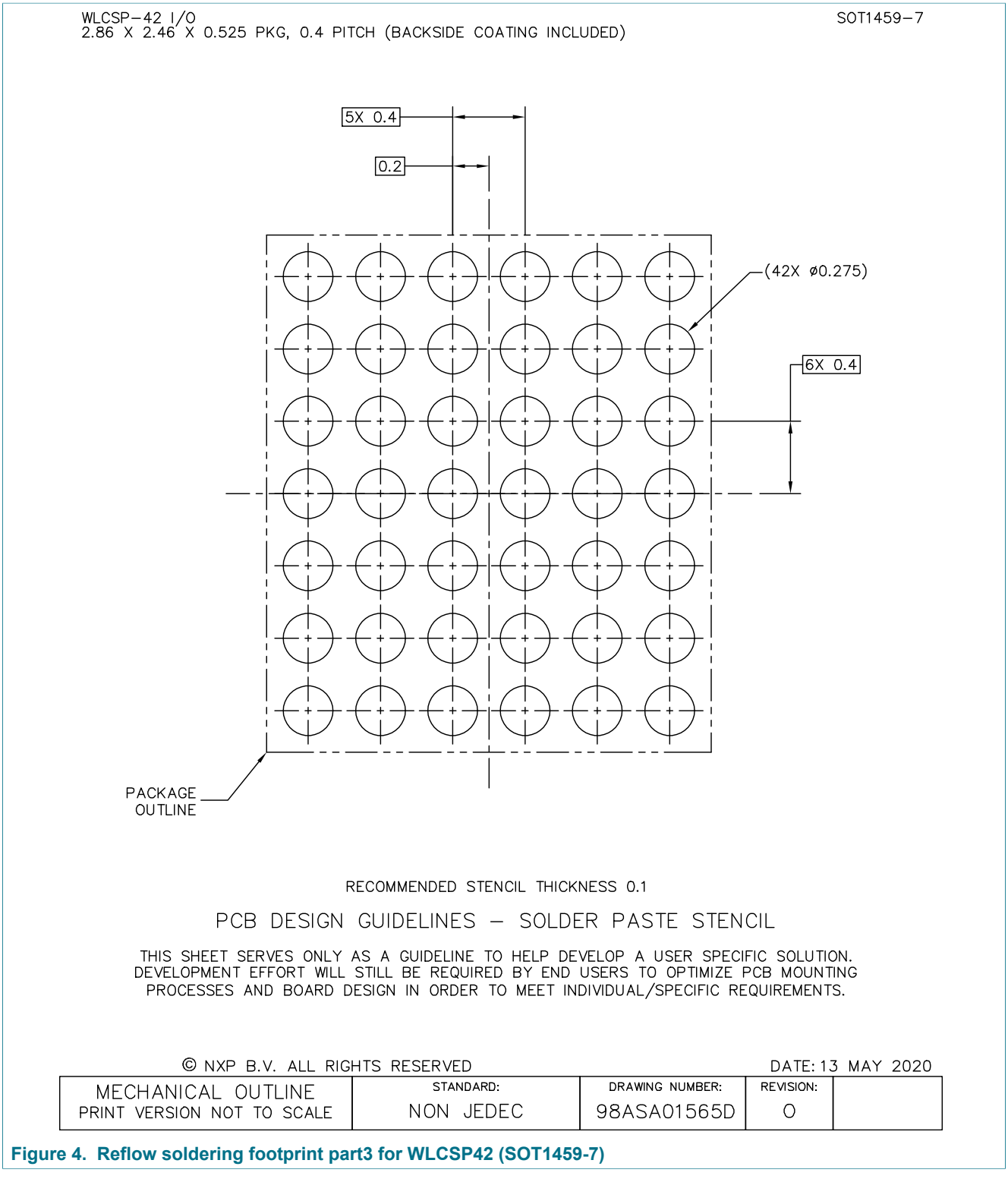

Figure 4. Reflow soldering footprint part3 for WLCSP42 (SOT1459-7)

WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 2.86 mm x 2.46 mm x 0.525 mm body (backside coating included)

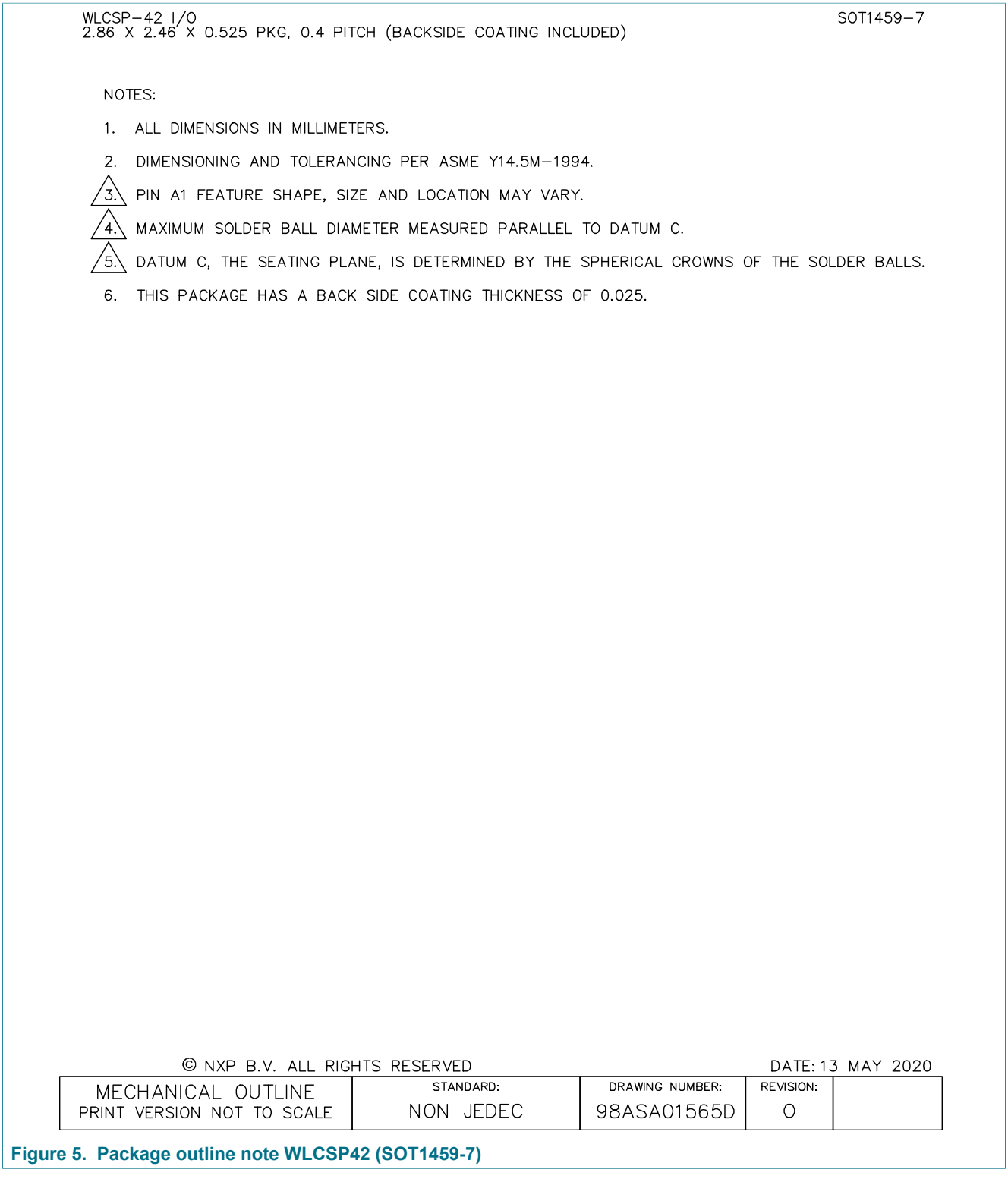

Figure 5. Package outline note WLCSP42 (SOT1459-7)

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SOT1459-7

WLCSP42, wafer level chip scale package, 42 terminals, 0.4 mm pitch, 2.86 mm x 2.46 mm x 0.525 mm body (backside coating included)

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Date of release: 25 May 2020